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(54) **PACKAGING PROCESS FOR EMBEDDED CHIPS**

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ABSTRACT

A packaging process for embedded chips includes: (1) mounting at least one IC chip on a circuit substrate, the IC chip having at least one exposed pin; (2) attaching a self-adhesive copper foil film to the surface of the circuit substrate, wherein the self-adhesive copper foil film has a copper foil layer and a B-stage insulating adhesive layer, the copper foil layer has at least one to-be-opened copper foil area corresponding to the pin, the insulating adhesive layer is applied on the copper foil layer, has no glass fiber, covers the IC chip, and has at least one to-be-opened insulating adhesive area corresponding to the pin, and the pin is in contact with the insulating adhesive layer but not with the copper foil layer; (3) removing the to-be-opened copper foil area; (4) removing the to-be-opened insulating adhesive area with an etching solution; and (5) curing the insulating adhesive layer completely.

